



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

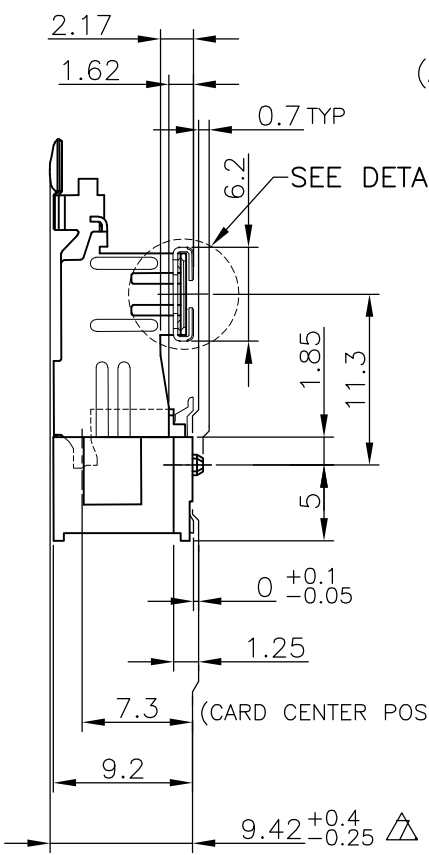
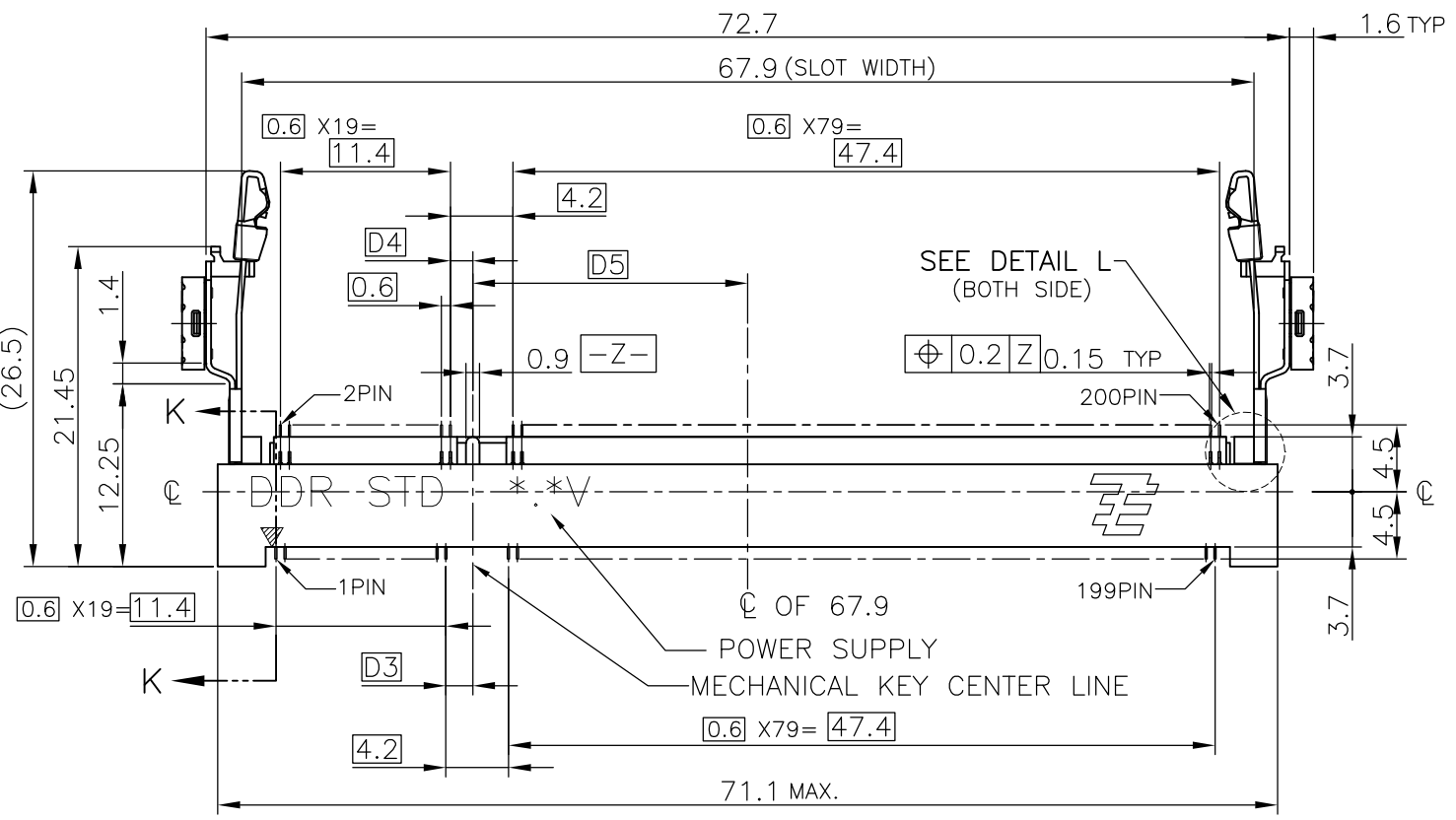
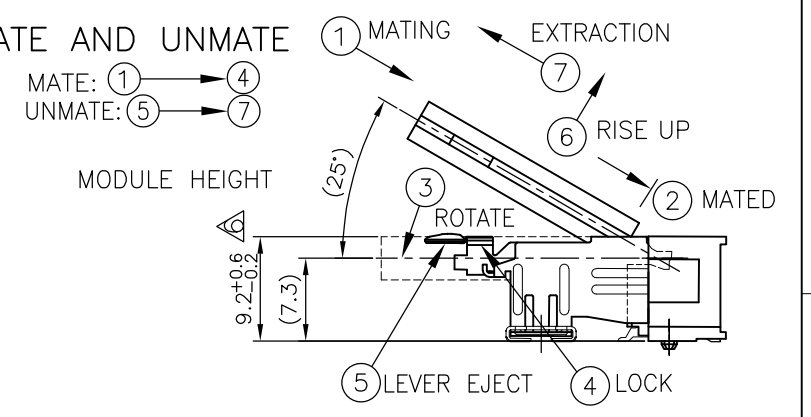
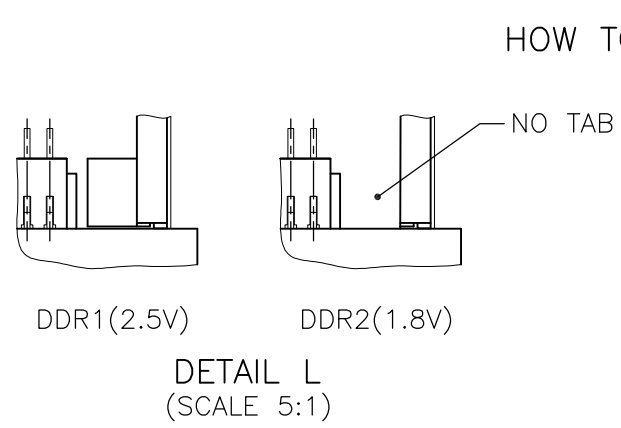
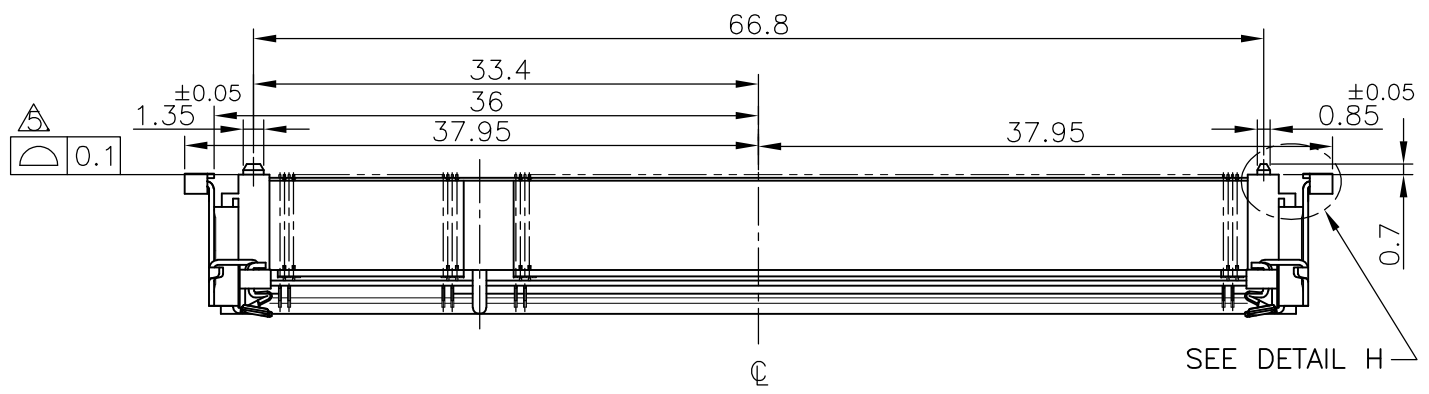
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

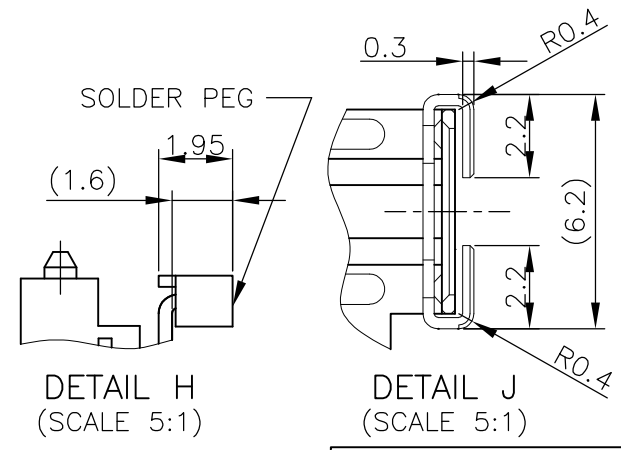
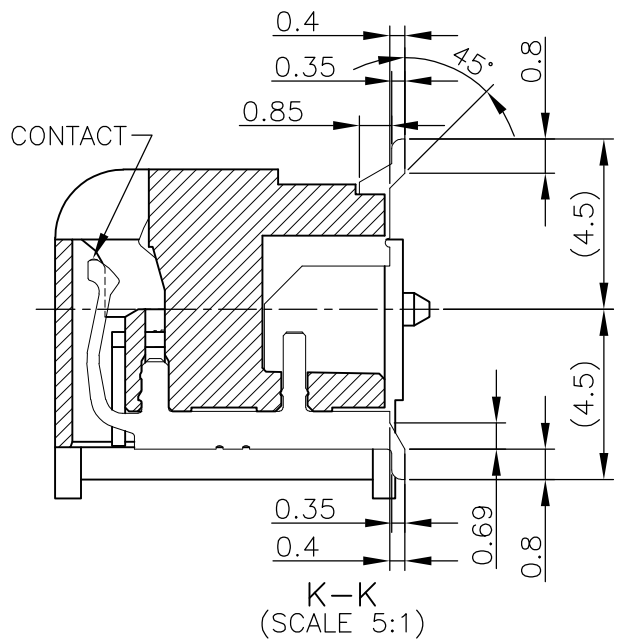


THIS DRAWING IS UNPUBLISHED. RELEASED FOR PUBLICATION OCT. 2002.  
 © COPYRIGHT 2002 By - ALL RIGHTS RESERVED.

LOC		DIST		REVISIONS			
ES	/	P	LTR	DESCRIPTION	DATE	DWN	APVD
			E3	REVISED PER ECO-11-005033	26MAR11	RK	HMR



- (APPLIED TO SHEET 1-2)
- MATERIAL ; HOUSING: HIGH TEMPERATURE THERMO PLASTIC UL94V-0  
 CONTACT: COPPER ARROY  
 LOCK LEVER: STAINLESS STEEL  
 SOLDER PEG: COPPER ARROY
  - FINISH ; CONTACT AREA: GOLD FLASH ON 0.0013MIN ALL OVER NICKEL.  
 SOLDERING AREA: GOLD FLASH PLT.  
 SOLDER PEG: TIN PLATING.
- MECHANICAL KEY POSITION OF CONNECTOR SEE TABLE.
  - TOLERANCES NON-CUMULATIVE.
  - COPLANARITY : 0.1 MAX.
  - THE FLOATING VALUE BY SOLDERING IS NOT INCLUDED.
  - NOT MATING CONDITION.
  - IF THE MODULE DOESN'T INSERT AND LOCK IN THE LATCH SMOOTHLY, OPEN WIDE BOTH LATCHES BY MANUAL. AND THE MODULE MUST BE INSERTED AND LOCKED IN THE LATCH.
  - THE SHAPE OF HOUSING AT KEY AREA IS FREE BASICALLY TO IMPROVE HOUSING WARPAGE



GENERAL TOLERANCE  
 10 ≥ : ±0.2  
 30 ≥ > 10: ±0.25  
 100 ≥ > 30: ±0.3  
 ANGLES: ±3'

AVAILABLE	1.8V (DDR2)	17.55	2.4	2.7	200	1612618-4
AVAILABLE	2.5V (DDR1)	18.45	1.5	1.8	200	1612618-1
TOOLING STATUS	POWER SUPPLY (TYPE)	D5	D4	D3	POS	PART NO.

THIS DRAWING IS A CONTROLLED DOCUMENT.

DWN	J.TANIGAWA	21OCT02
CHK	H.KODAMA	21OCT02
APVD	I.ENOMOTO	21OCT02
PRODUCT SPEC	108-5701	
APPLICATION SPEC		
WEIGHT	8.3g	

STE TE Connectivity

DDR1 & DDR2 SODIMM SOCKET  
 0.6mm PITCH 200POS  
 9.2mm HEIGHT STANDARD TYPE

SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO
A3	00779	C-1612618	

CUSTOMER DRAWING SCALE 2:1 SHEET 1 OF 4 REV E3

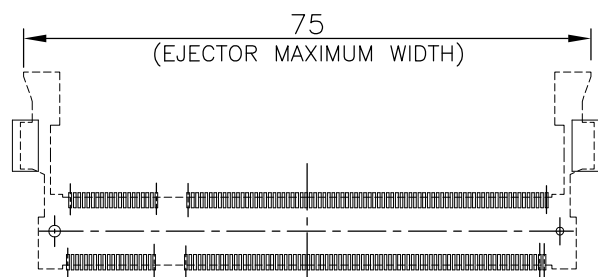
THIS DRAWING IS UNPUBLISHED.

RELEASED FOR PUBLICATION OCT ,2002.

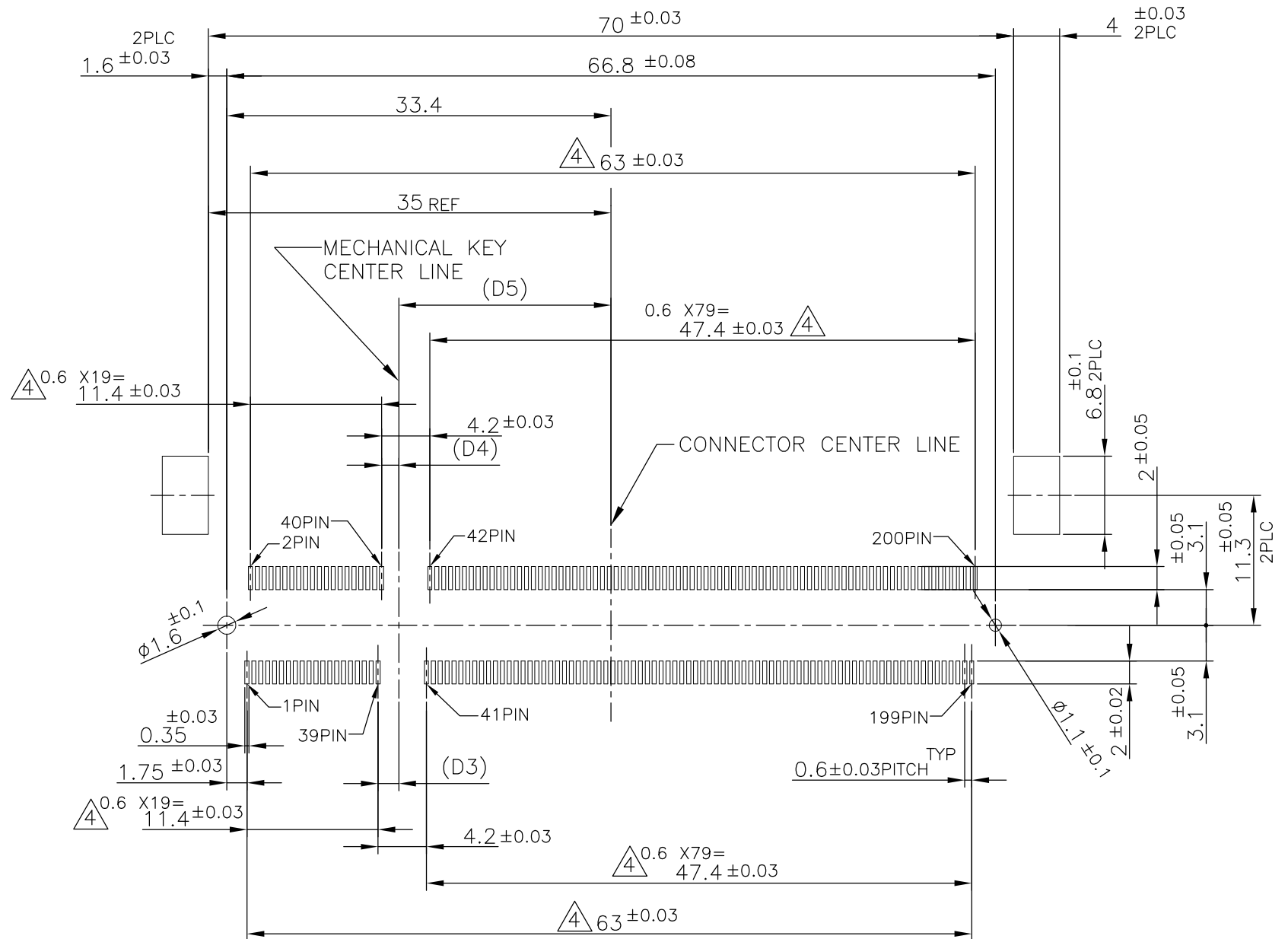
© COPYRIGHT 2002 By -

ALL RIGHTS RESERVED.

LOC	DIST	REVISIONS			
P	LTR	DESCRIPTION	DATE	DWN	APVD
ES		SEE SHEET 1	-	-	-



REAL SIZE (SCALE 1:1)

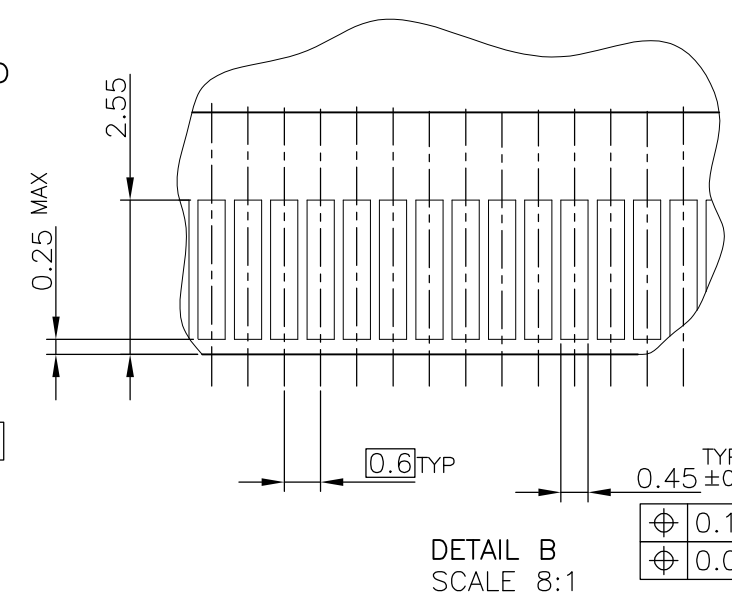
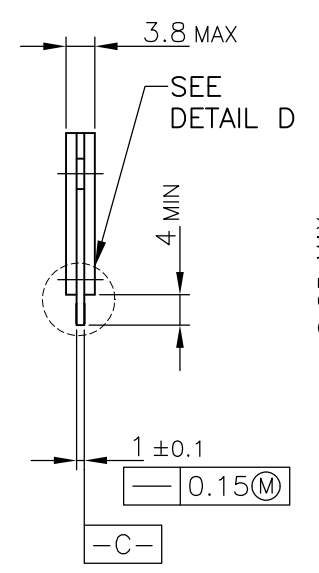
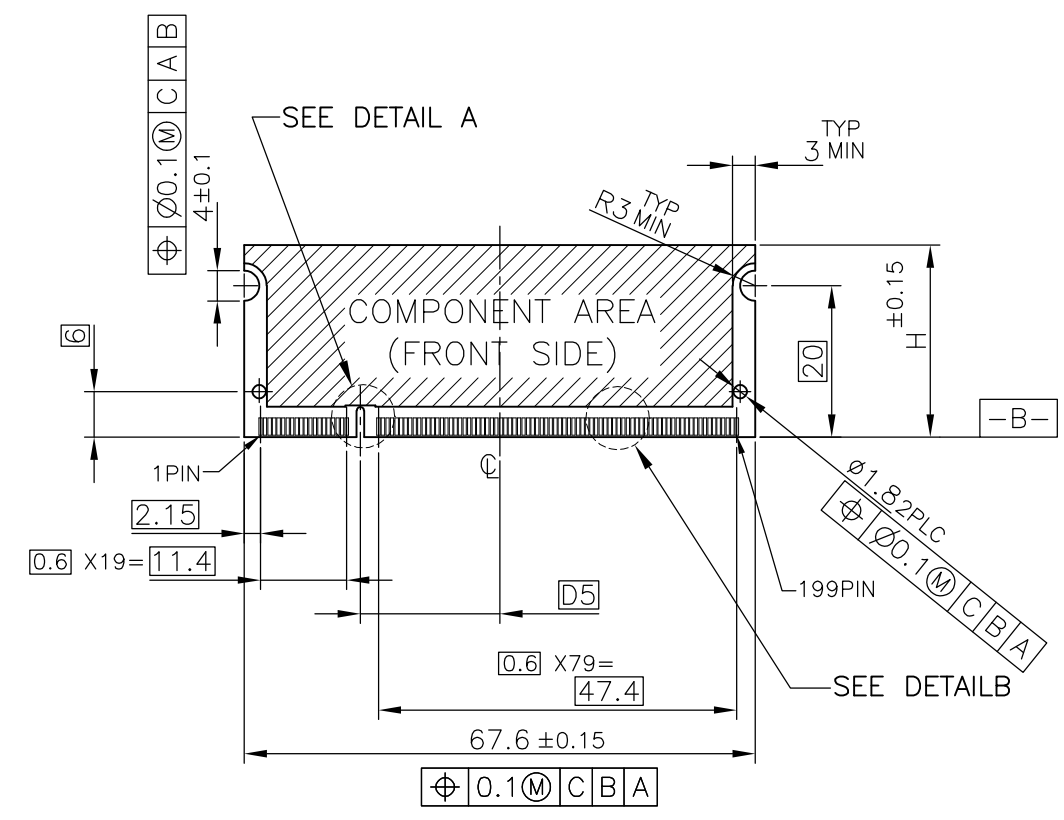


REFERENCE P.C. BOARD PATTERN LAYOUT FOR DUAL USE (CONNECTOR MOUNTING SIDE)

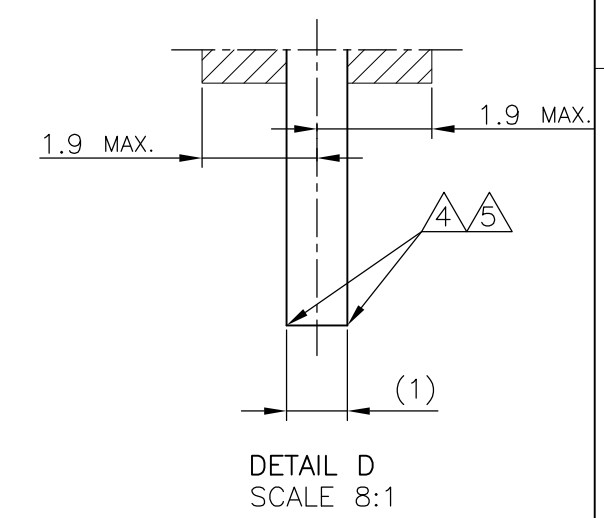
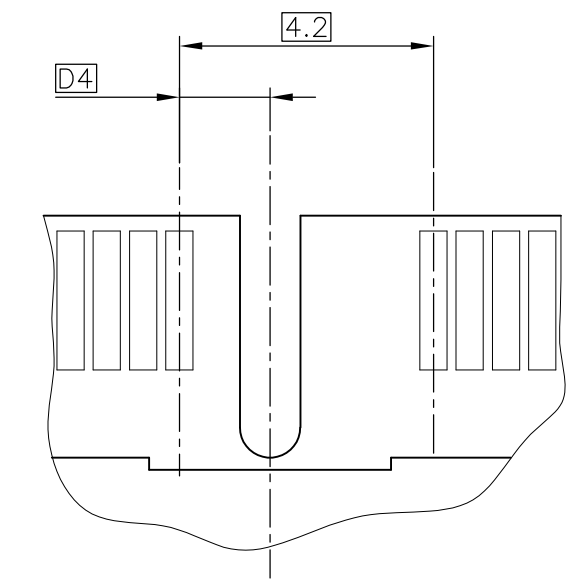
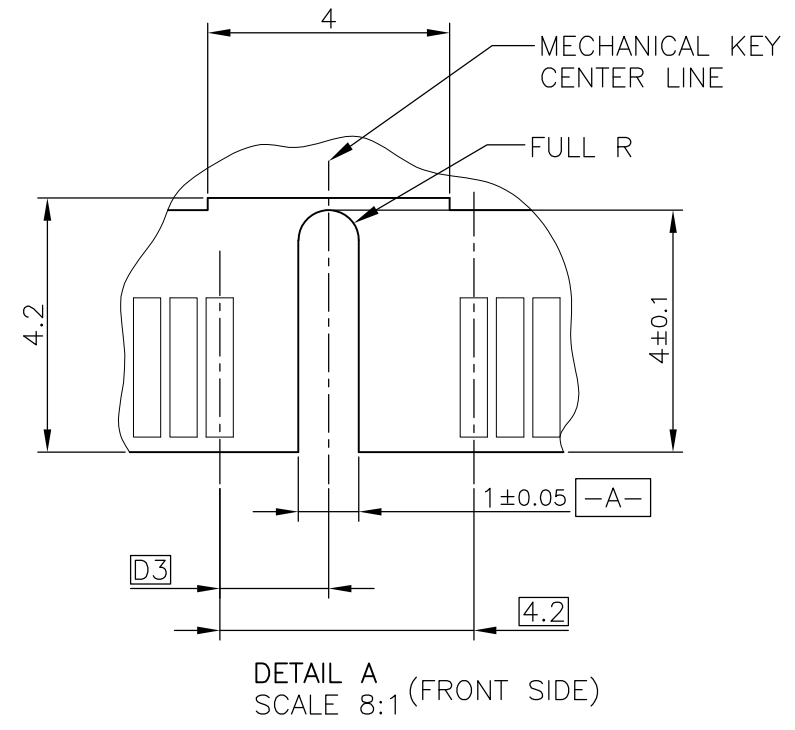
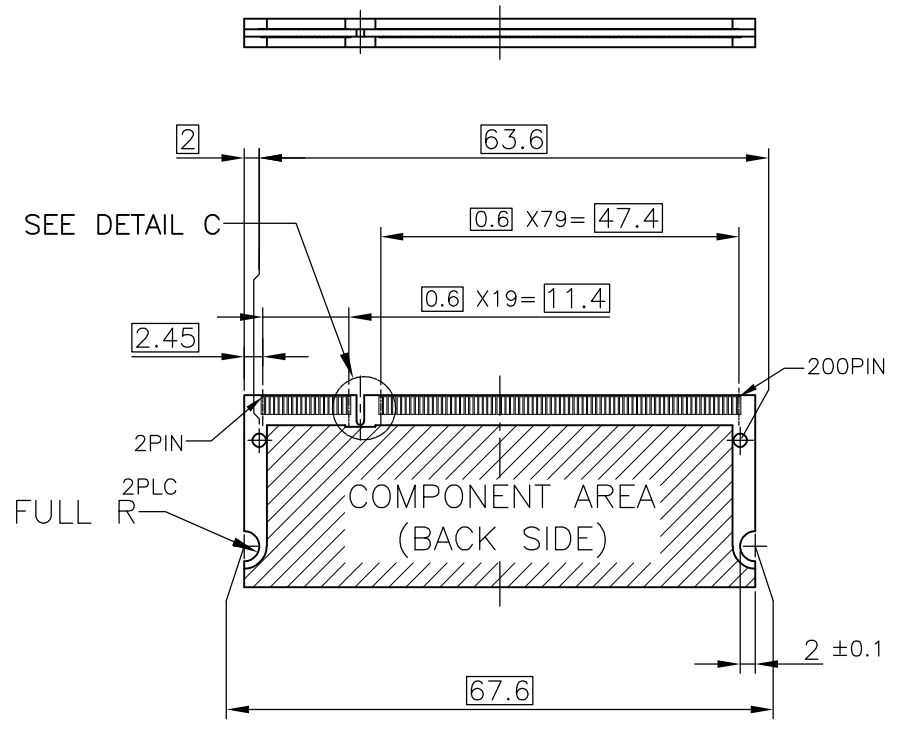
THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN	<b>STE</b> TE Connectivity		
DIMENSIONS: MM		CHK			
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD	NAME		
0 PLC ±		PRODUCT SPEC	DDR1 & DDR2 SODIMM SOCKET		
1 PLC ±		APPLICATION SPEC	0.6mm PITCH 200POS		
2 PLC ±		WEIGHT	SIZE	CAGE CODE	DRAWING NO
3 PLC ±		CUSTOMER DRAWING	A3	00779	C-1612618
4 PLC ±			SCALE	SHEET	REV
ANGLES ±		RESTRICTED TO	NTS	2 OF 4	E3
FINISH					

THIS DRAWING IS UNPUBLISHED. RELEASED FOR PUBLICATION OCT. 2002. ALL RIGHTS RESERVED.

LOC ES	DIST	REVISIONS					
		P	LTR	DESCRIPTION	DATE	DWN	APVD
		-	-	SEE SHEET 1	-	-	-



- (APPLIED TO SHEET 3)
- 1 TOLERANCES ON ALL DIMENSIONS ±0.15 UNLESS OTHERWISE SPECIFIED.
  - 2 P.C. BOARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR METALIZATION.
  - 3 FINISH OF PAD : GOLD PLATING 0.00076 MIN. OVER Ni PLATING 0.002MIN.
- △ NO BURR.
- △ CHAMFER 0.25 MAX x 45° IF EXIST.



推奨基板仕様  
RECOMMENDED MATING P.C.B CONFIGURATION

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: MM	TOLERANCES UNLESS OTHERWISE SPECIFIED:
	0 PLC ±
	1 PLC ±
	2 PLC ±
	3 PLC ±
	4 PLC ±
	ANGLES ±
MATERIAL	FINISH ±

DWN
CHK
APVD
PRODUCT SPEC
APPLICATION SPEC
WEIGHT
CUSTOMER DRAWING

31.75	1.8V	17.55	2.4	2.7
25.4	2.5V	18.45	1.5	1.8
H	POWER SUPPLY	D5	D4	D3

**STE** TE Connectivity

NAME: DDR1 & DDR2 SODIMM SOCKET  
0.6mm PITCH 200POS  
9.2mm HEIGHT STANDARD TYPE

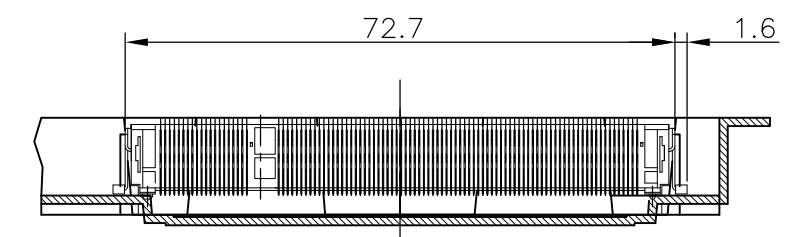
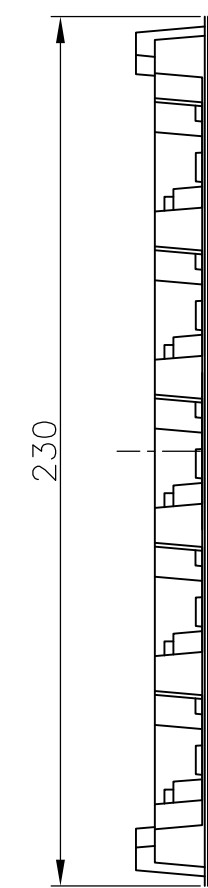
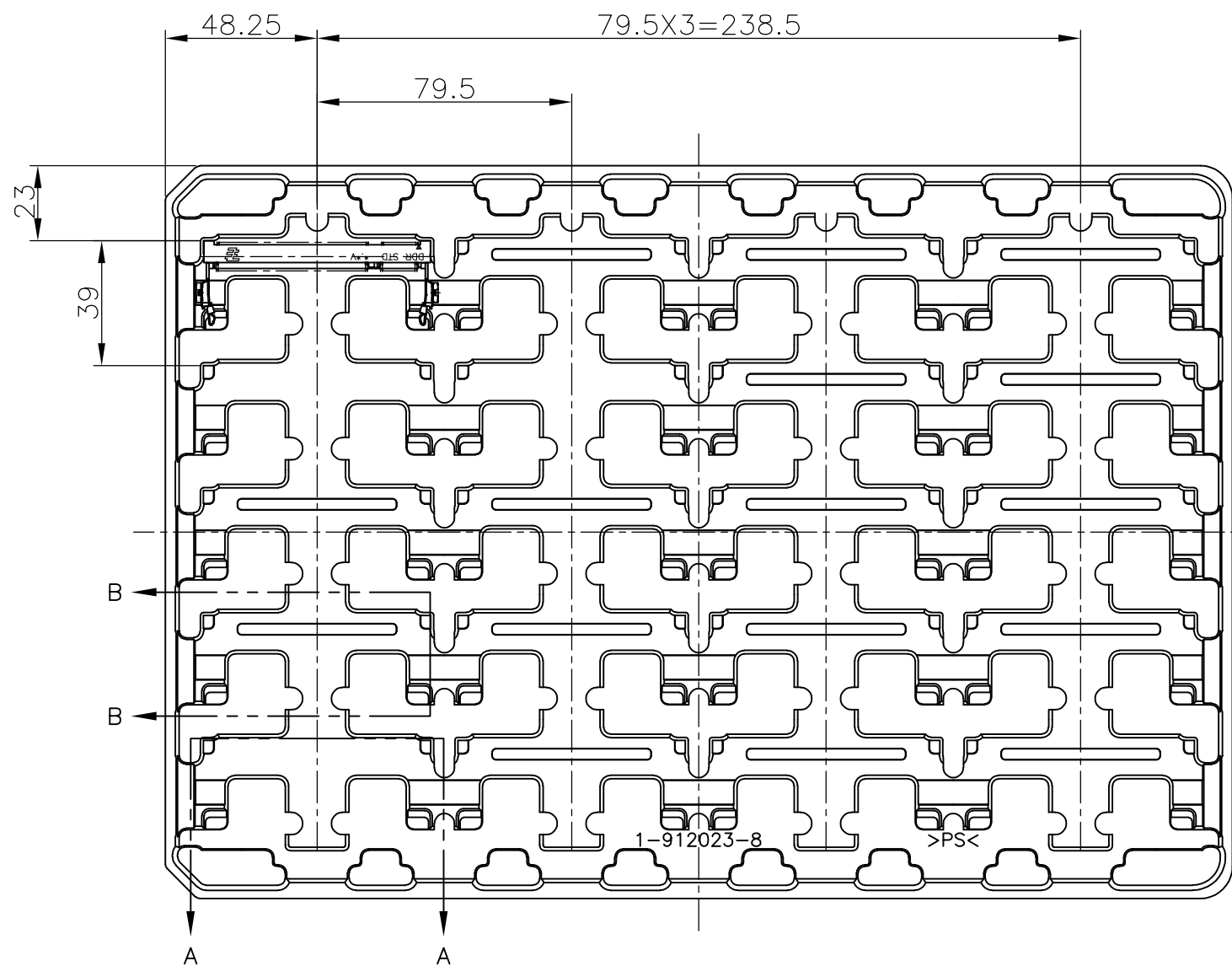
SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO
A3	00779	C-1612618	

SCALE: NTS SHEET: 3 OF 4 REV: E3

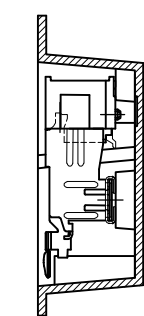


THIS DRAWING IS UNPUBLISHED. RELEASED FOR PUBLICATION OCT , 2002.  
 © COPYRIGHT 2002 By - ALL RIGHTS RESERVED.

LOC	DIST	REVISIONS			
P	LTR	DESCRIPTION	DATE	DWN	APVD
ES		SEE SHEET 1	-	-	-

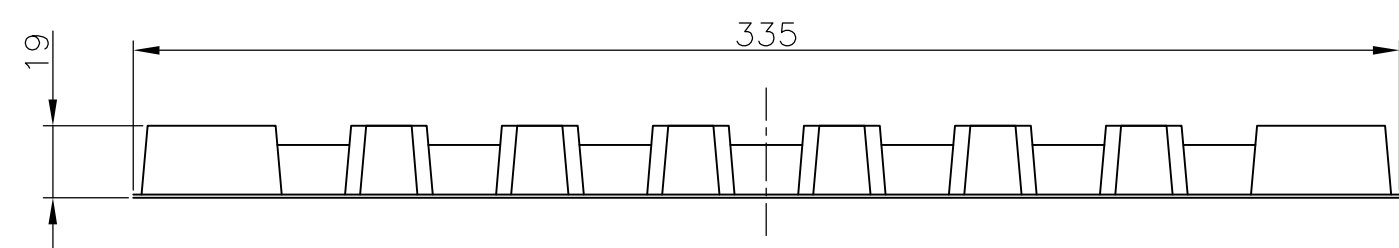


A-A  
SCALE 1:1  
(180DEG. ROTATE)



B-B  
SCALE 1:1

1. THE DIRECTION OF EACH CONNECTOR ON A TRAY IS REFERRED TO THIS DRAWING.
2. GENERAL TOLERANCE: ±0.5



20EA/TRAY	1612618-4
20EA/TRAY	1612618-1
QTY	P/N

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN	TE Connectivity NAME DDR1 & DDR2 SODIMM SOCKET 0.6mm PITCH 200POS 9.2mm HEIGHT STANDARD TYPE				
DIMENSIONS: MM		CHK					
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD					
0 PLC ± 0.5 1 PLC ± 0.5 2 PLC ± 0.5 3 PLC ± 0.5 4 PLC ± 0.5 ANGLES ± 3°		PRODUCT SPEC					
MATERIAL		FINISH	APPLICATION SPEC	SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO
			WEIGHT	A3	00779	C-1612618	
CUSTOMER DRAWING			SCALE	1:2	SHEET	4 OF 4	REV E3